

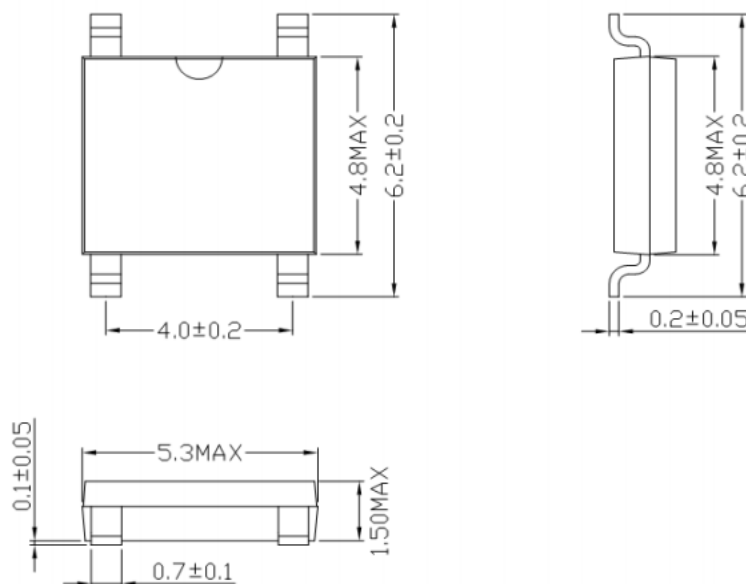


Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material -UL Flammability 94V-0

Mechanical Data

- Case: SOPA-4, Mold Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Case
- Mounting Position: Any
- Marking: Type Number



Maximum Ratings and Electrical Characteristics @TA=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbol	ABS2	ABS4	ABS6	ABS8	ABS10	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	800	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum Average forward output rectified current on glass-epoxy P.C.B on aluminum substrate	$I(AV)$	0.8 1.0					A
Peak forward surge current 8.3ms single sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30					A
Maximum instantaneous forward voltage drop per diode @0.4A	V_F	1.0					V
Maximum DC reverse current at TA=25°C rated DC blocking voltage per leg TA=125°C	I_R	5.0 500					μA
Typical thermal resistance per leg (Note 1)	$R_{\theta JA}$	80					°C/W
	$R_{\theta JL}$	25					
Operating junction temperature range	T_J	-55 to +150					°C
storage temperature range	T_{stg}	-55 to +150					°C

Note:

1. Device mounted P.C.B with 0.47x0.47" (12mmx12mm) Copper Pads.



Characteristic Curves ($T_A=25$ unless otherwise noted)

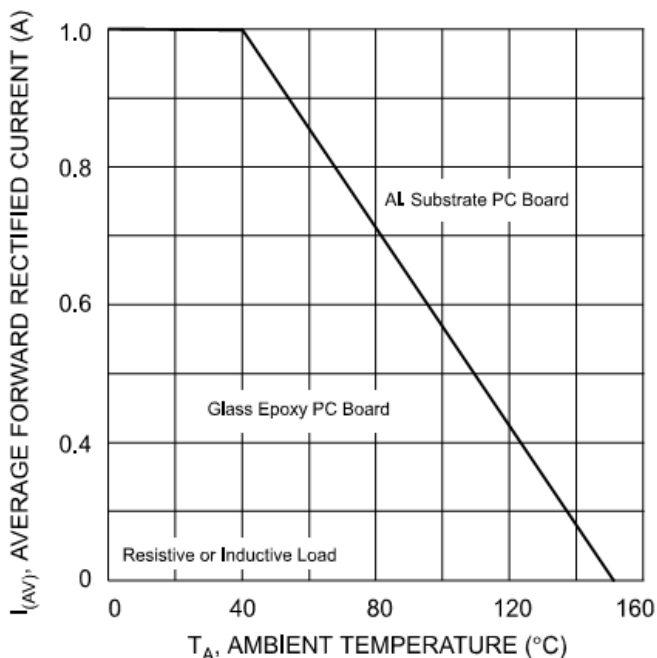


Fig. 1 Output Current Derating Curve

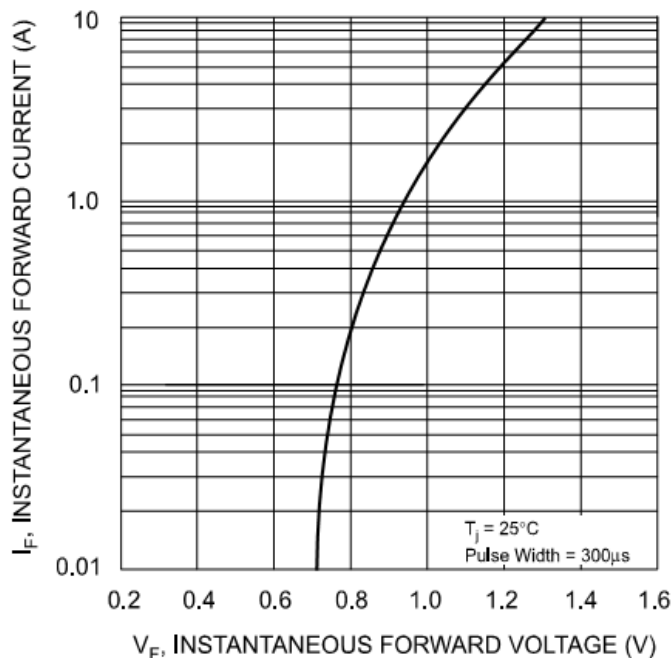


Fig. 2 Typical Forward Characteristics (per leg)

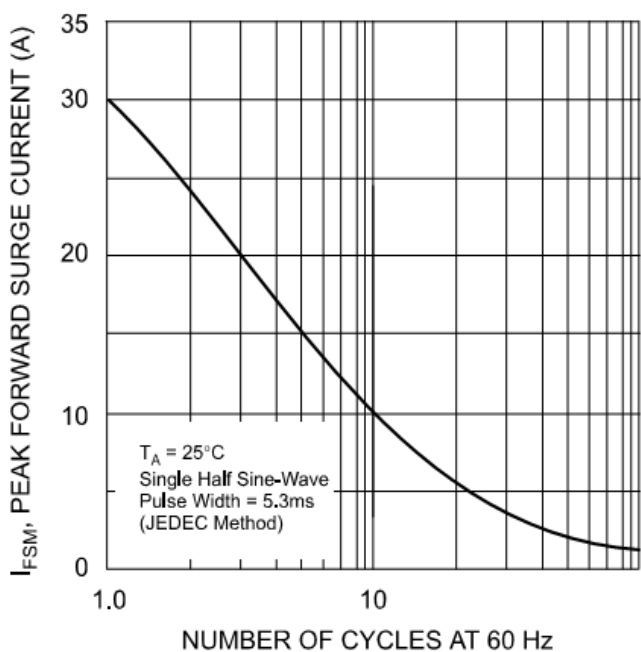


Fig. 3 Maximum Peak Forward Surge Current (per leg)

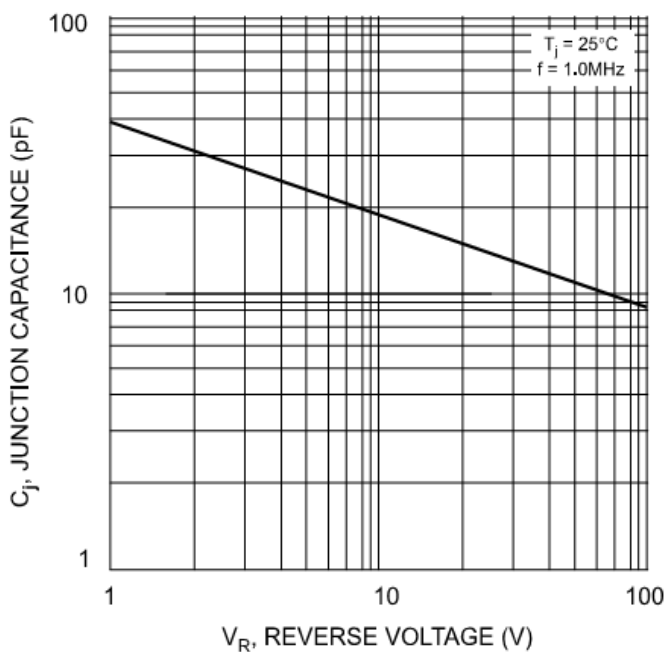


Fig. 4 Typical Junction Capacitance

